



100% Material Declaration Data Sheet for 7 Series SBG484

PK600 (v1.0) February 15, 2013

Average Weight: 1.4728g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.237468	16.123
	Silicon (Si)	7440-21-3	100.00	basis	0.237468	
Solder Bump					0.011261	0.765
	Tin (Sn)	7440-31-5	63.00	basis	0.007094	
	Lead (Pb)	7439-92-1	37.00	basis	0.004167	
Underfill					0.035000	2.376
	Bisphenol F/ epichlorohydrin copolymer	9003-36-5	20.00	basis	0.007000	
	Phenolic resin	trade secret	15.00	basis	0.005250	
	Bisphenol A type liquid epoxy resin	25068-38-6	5.00	basis	0.001750	
	Amine type accelerator	trade secret	5.00	basis	0.001750	
	Silicon dioxide	60676-86-0	51.50	basis	0.018025	
	Carbon black	1333-86-4	1.00	basis	0.000350	
	Additives	trade secret	2.50	Additive	0.000875	
Solder Ball					0.233980	15.887
	Sn	7440-31-5	96.50	Main material	0.225791	
	Ag	7440-22-4	3.00	Main material	0.007019	
	Cu	7440-50-8	0.50	Main material	0.001170	
Substrate					0.955101	64.849
	Copper (Cu)	7440-50-8	36.72		0.350689	
	Tin (Sn)	7440-31-5	1.38		0.013140	
	Lead (Pb)	7439-92-1	0.41		0.003876	
	Silver (Ag)	7440-22-4	0.02		0.000203	
	BT Core	trade secret	47.75		0.456088	
	ABF	trade secret	11.22		0.107127	
	Solder Mask	trade secret	2.51		0.023978	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
02/15/2013	1.0	Initial Xilinx release.

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